Schedule of Scope to Certificate of Approval

Approved Process - Capability Approval

IECQ Certificate No.: IECQ-C BSI 14.0010

CB Certificate No.: E015/CA

Board Types:	Rigid single and double-sided with plain holes	BS CECC 23100-003
	Rigid double-sided with plated-through holes	BS CECC 23200-003
	Rigid multi-layer	BS CECC 23300-003 CECC 23300-003
	Flexible single and double sided without-through connections	CECC 23400-003
	Flexible single and double-sided with through-connections	CECC 23500-003
	Flex-rigid multi-layer with through-connections	BS CECC 23600-801
	Flex-rigid double-sided with through-connections	BS CECC 23700-801
	Flexible Multi-layer with through connections	BS CECC 23800-801

Base Materials:
Epoxide Woven Glass
Polyimide Woven Glass
Polyimide Film
Acrylic and Epoxide Adhesive

Board Size:	580 mm	x 430 mm	Maximum	BS EN 123 300
	580 mm	x 430 mm	Maximum	BS EN 123 100, 200
	430 mm	x 370 mm	Maximum	BS EN 123 400, 500, 600, 700, 800

Number of Layers:	24	Maximum	BS EN 123 300
	12	Maximum	BS EN 123 600

Conductors:	Minimum Width:	80 μm	± 30 %
	Minimum Spacing:	80 μm	± 30 %

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Plated through Hole Diameter:	0.45 mm 0.30 mm	Minimum (finished) Minimum (drilled)	for component mounting via hole

Aspect Ratio: 9.1 : 1 Maximum

Finishes:
*Electroplated Tin-Lead
*Tin-Lead; IR or Hot Oil fused
*Hot Air Solder Levelling
*Selective Nickel / Tin lead
Electroless Nickel/Gold;
2.5μm Gold over Nickel Edge Contacts
2.5μm Gold over Copper Edge Contacts

Organic Finishes:
Photopolymer solder resist, imageable liquid resist
Solder resist, oven or UV cured
Legend, oven or UV cured

Additional:
Epoxide Woven Glass Stiffeners
Blind vias / Micro vias /Buried Vias
(Adjacent, Non-adjacent layers & >2 layers)

Bonded Heat Sinks surface / sandwiched
- Copper
- Aluminium

*These features meet the requirements for accelerated ageing when tested in accordance with BS 6221 Part 2,14a.

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Demonstration of Impedance Control:

Board types:	Rigid double sided with plated-through holes.	BS CECC 23200-003
	Rigid Multilayer	BS CECC 23300-003
Materials:	Epoxide Woven Glass Polyimide Woven Glass	
Board Size:	458 mm x 372 mm Maximum	
No. of Layers:	24 Maximum	
Conductors:	Minimum Width Minimum Spacing	100 µm ±50 µm 100 µm ±50 µm
Impedance Demonstrated:	50 Ω to 110 Ω	
Declared Tolerance:	±7 % to ±25 % (as defined in the Customer Detail Specification)	
Geometries:	Stripline Microstrip Differential Impedance	

This supplement describes the manufacturer's capability to produce printed boards which feature control of characteristic impedance, as described in clause 4.1.4 of BS CECC 23300-003.

Not all features can be achieved in combination.

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